Chinastandards.org

ICS 31.030
CCS L 90

SJ

# INDUSTRY STANDARD OF THE PEOPLE'S REPUBLIC OF CHINA

# SJ/T 12005-2025

## Active metal brazing (AMB) silicon nitride ceramic copper-clad substrate for power semiconductor packaging

**(English Translation)**

**Issued on: September 9, 2025** **Implemented on: March 1, 2026**

**Issued by: Ministry of Industry and Information Technology**

Preview: page 1 of 2 shown, 9 in the full document. Complete English PDF, instant download:
https://chinastandards.org/standards/sj-t-12005-2025

Chinastandards.org

# Table of Contents

What this standard covers ..... 1
Document data ..... 2

## What this standard covers

This standard specifies the requirements, test methods, inspection rules, marking, packaging, transportation, and storage for Active Metal Brazing (AMB) silicon nitride ceramic copper-clad substrates used in power semiconductor packaging. It applies to silicon nitride ceramic copper-clad substrates manufactured using the AMB process.

## Document data

International classification (ICS): 31.030.

Chinese classification (CCS): L90.

Estimated length of the Chinese original: 13,179 words.



Preview: page 2 of 2 shown, 9 in the full document. Complete English PDF, instant download:
https://chinastandards.org/standards/sj-t-12005-2025